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(54) **Title**: APPARATUS AND METHOD FOR TAPING ADHESIVE FILM ON SEMICONDUCTOR SUBSTRATE

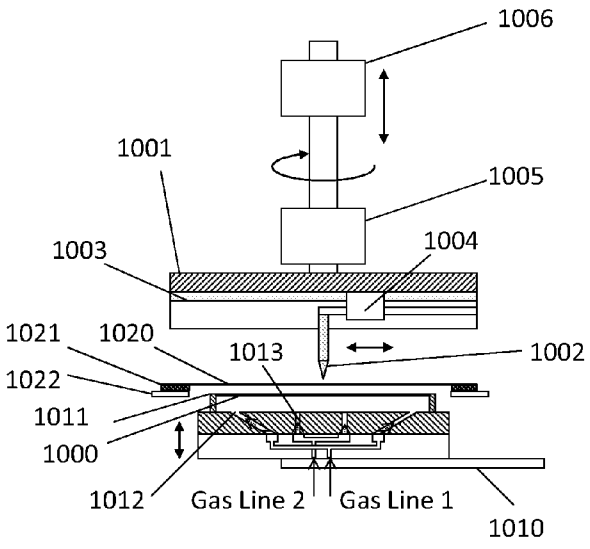


FIG. 1B

(57) **Abstract**: The present invention discloses an apparatus and a method for taping adhesive film on semiconductor substrate. In one embodiment, the apparatus includes: a support arm holding a semiconductor substrate; a stage loading and locating an adhesive film above the semiconductor substrate; a rotating plate having a linear rail and being positioned over the adhesive film; a linear actuator mounted on the linear rail and being capable of moving along the linear rail; a gas nozzle supplying taping gas onto the adhesive film for pressing the adhesive film onto the adhesive side of the semiconductor substrate, the gas nozzle fixed on the linear actuator and moving together with the linear actuator; and a rotating actuator connected to the rotating plate and driving the rotating plate to rotate in a plane parallel to the plane of the semiconductor substrate.

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